

UNITED STATES PATENT AND TRADEMARK OFFICE
CERTIFICATE OF CORRECTION

PATENT NO. : 6,746,591 B2
APPLICATION NO. : 09/981508
DATED : June 8, 2004
INVENTOR(S) : Bo Zheng, Renren He and Girish Dixit

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

On the cover page in the Title, change "Voltate" to --Voltage--, to read --ECP GAP FILL BY MODULATING THE VOLTAGE ON THE SEED LAYER TO INCREASE COPPER CONCENTRATION INSIDE FEATURE--;

The Abstract should read:

A method for electro-chemically depositing a metal onto a substrate. The method generally includes providing an electrolyte container configured to receive and maintain a fluid electrolyte therein, the electrolyte container having an anode disposed within the electrolyte container, providing a head assembly positioned above the electrolyte container, the head assembly including a wafer holder for supporting a wafer and a cathode, and positioning a wafer in the electrolyte container in contact with the fluid electrolyte, and applying a varying amplitude waveform to the cathode and anode in an electroplating process.

Column 1, line 2, in the Title, change "Voltate" to -- Voltage --;

Column 1, line 43, change "it's" to --its--;

Column 1, line 49, change "it's" to --its--;

Column 3, line 19, insert --to-- after "configured";

Column 6, line 52, change "conducting" to -- conducting--;

Column 10, in Claim 12, line 66, delete "8" after "50";

Signed and Sealed this

Fourteenth Day of August, 2007



JON W. DUDAS
Director of the United States Patent and Trademark Office